Amendments to the Specification

Please replace paragraph [0016] with the following amended paragraph:

[0016] The invention relates, in one embodiment, to a method in a plasma processing system of removing a set of particles from a set of structures including yttrium oxide. The method includes exposing the set of structures to a first solution including an oxidizer for a first period. The method also includes removing the set of structures from the first solution, and exposing the set of structures to a second solution including a ~~keytone~~ ketone reagent for a second period. The method further includes removing the set of structures from the second solution, and mechanically rubbing the set of structures with a third solution including a first set of acids for a third period.

Please replace paragraph [0037] with the following amended paragraph:

[0037] While exposed, the structure is mechanically rubbed to loosen by-product deposits, at step 404. The structure is then removed, rinsed with DI (de-ionized) water, and dried by a filtered inert gas, such as nitrogen, at step 406. The structure is then ultrasonically cleaned with a ~~keytone~~ ketone reagent, such as acetone, and periodically mechanically rubbed, at step 408. The structure is then removed from the ~~keytone~~ ketone reagent, rinsed with DI water, and again dried by a filtered inert gas, at step 410. The structure is rinsed and mechanically rubbed with an alcohol, such as isopropyl alcohol, at step 412. This step should be repeated as necessary.

Please replace paragraph [0042] with the following amended paragraph:

[0042] The structure is then again rinsed with DI water, and dried by a filtered inert gas, at step 416. The structure is then exposed to a weak acidic solution (comprising CH_3COOH) for a substantially long period (e.g., ~10 minute), at step 420. In once aspect of the invention, the weak acidic solution is acetic acid. In another aspect of the invention, the weak acidic solution comprises from about 2% to about 10% of ~~the solution~~ CH_3COOH. In another aspect of the invention, the weak

acidic solution comprises from about 2% to about 6% of ~~the solution~~ CH_3COOH. In another aspect of the invention, the weak acidic solution comprises from about 4% to about 5% of ~~the solution~~ CH_3COOH.